2N7002PW

60 V, 310 mA N-channel Trench MOSFET

Rev. 02 — 29 July 2010 Product data sheet

1. Product profile

1.1 General description

N-channel enhancement mode Field-Effect Transistor (FET) in a very small SOT323 (SC-70) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

1.2 Features and benefits

- AEC-Q101 qualified
- Logic-level compatible
- Trench MOSFET technology
- Very fast switching

1.3 Applications

- High-speed line driver
- Low-side loadswitch
- Relay driver
- Switching circuits

1.4 Quick reference data

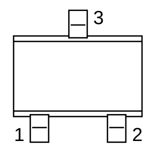
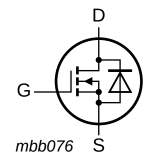
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DS}	drain-source voltage	T_{amb} = 25 °C		-	-	60	V
V_{GS}	gate-source voltage			-20	-	20	V
I_D	drain current	V_{GS} = 10 V; T_{amb} = 25 °C	[1]	-	-	310	mA
Static characteristics							
R_{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_D = 500 mA; T_j = 25 °C; t_p ≤ 300 μs; pulsed; δ ≤ 0.01		-	1	1.6	Ω

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm^2.

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 SOT323 (SC-70)	
2	S	source		
3	D	drain		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
2N7002PW	SC-70	plastic surface-mounted package; 3 leads	SOT323

4. Marking

Table 4. Marking codes

Type number	Marking code[1]
2N7002PW	X8%

[1] % = -: made in Hong Kong; % = p: made in Hong Kong; % = t: made in Malaysia; % = W: made in China

5. Limiting values

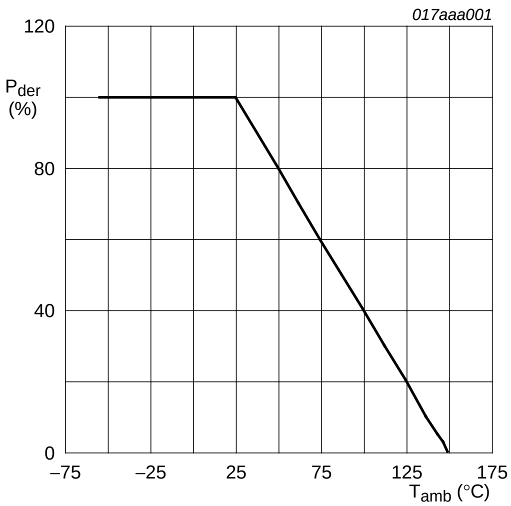
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage	T_{amb} = 25 °C		-	60	V
V_{GS}	gate-source voltage			-20	20	V
I_D	drain current	V_{GS} = 10 V; T_{amb} = 25 °C	[1]	-	310	mA
		V_{GS} = 10 V; T_{amb} = 100 °C	[1]	-	240	mA
I_{DM}	peak drain current	T_{amb} = 25 °C; single pulse; t_p ≤ 10 µs		-	1.2	A
P_{tot}	total power dissipation	T_{amb} = 25 °C	[2]	-	260	mW
			[1]	-	310	mW
		T_{sp} = 25 °C		-	830	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C
Source-drain diode						
I_S	source current	T_{amb} = 25 °C	[1]	-	310	mA

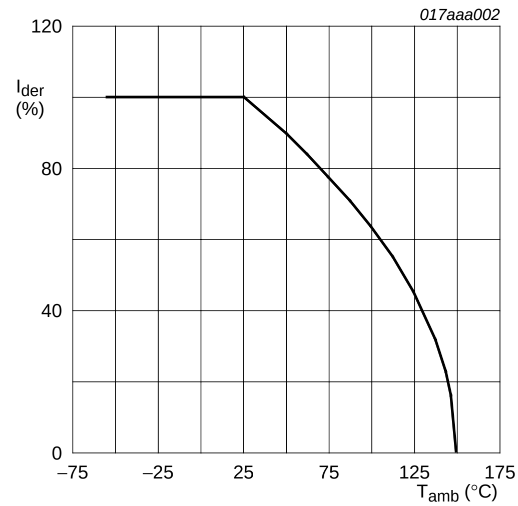
[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm^2.

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.



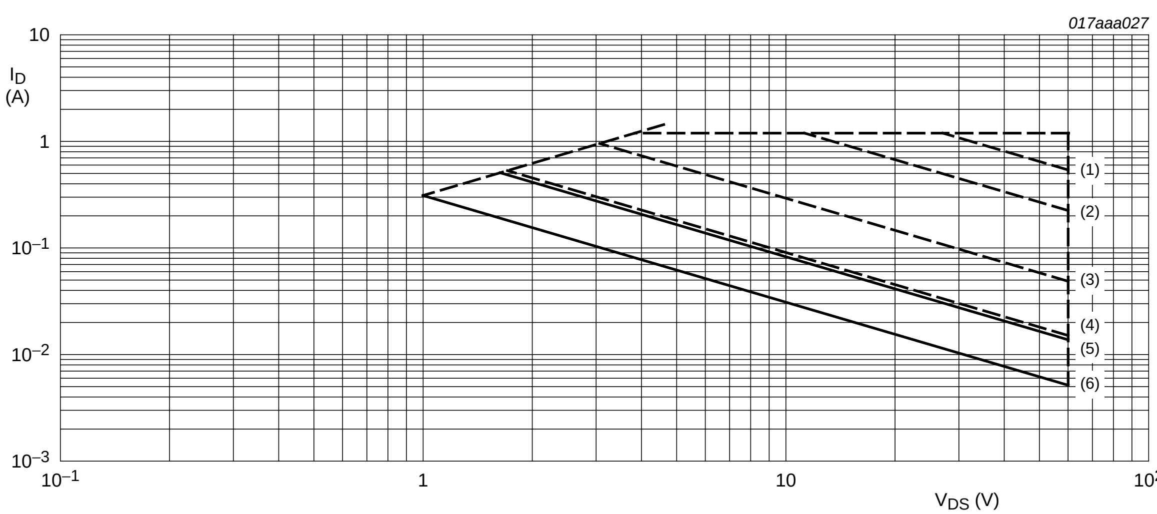
$$P_{der} = \frac{P_{tot}}{P_{tot(25°C)}} \times 100\ \%$$

Fig 1. Normalized total power dissipation as a function of ambient temperature



$$I_{der} = \frac{I_D}{I_{D(25°C)}} \times 100\ \%$$

Fig 2. Normalized continuous drain current as a function of ambient temperature



I_{DM} = single pulse

(1) t_p = 100 μs

(2) t_p = 1 ms

(3) t_p = 10 ms

(4) t_p = 100 ms

(5) DC; T_{sp} = 25 °C

(6) DC; T_{amb} = 25 °C; drain mounting pad 1 cm^2

Fig 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

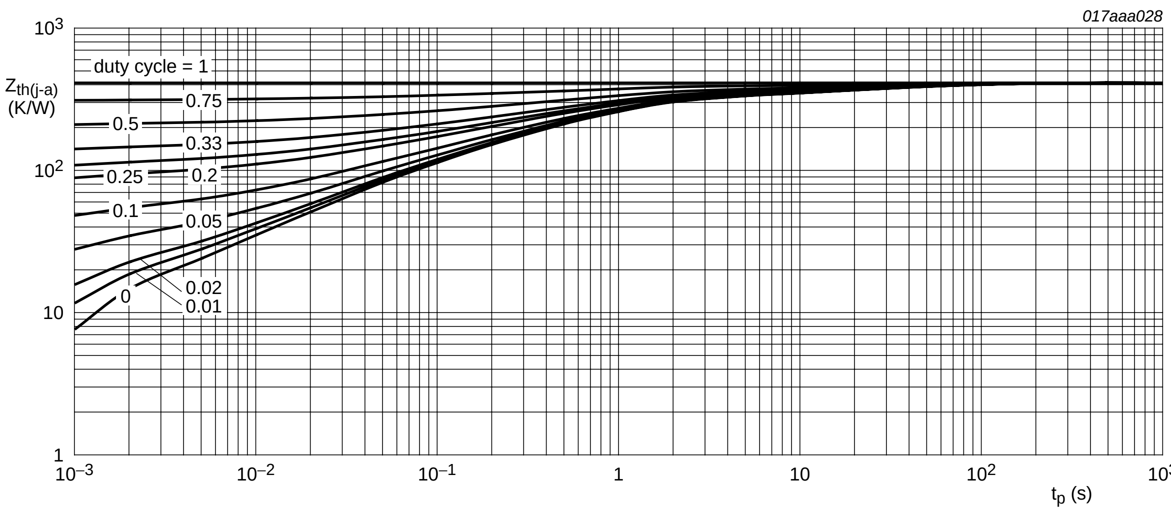
6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	415	480	K/W
			[2]	-	350	400	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	-	150	K/W

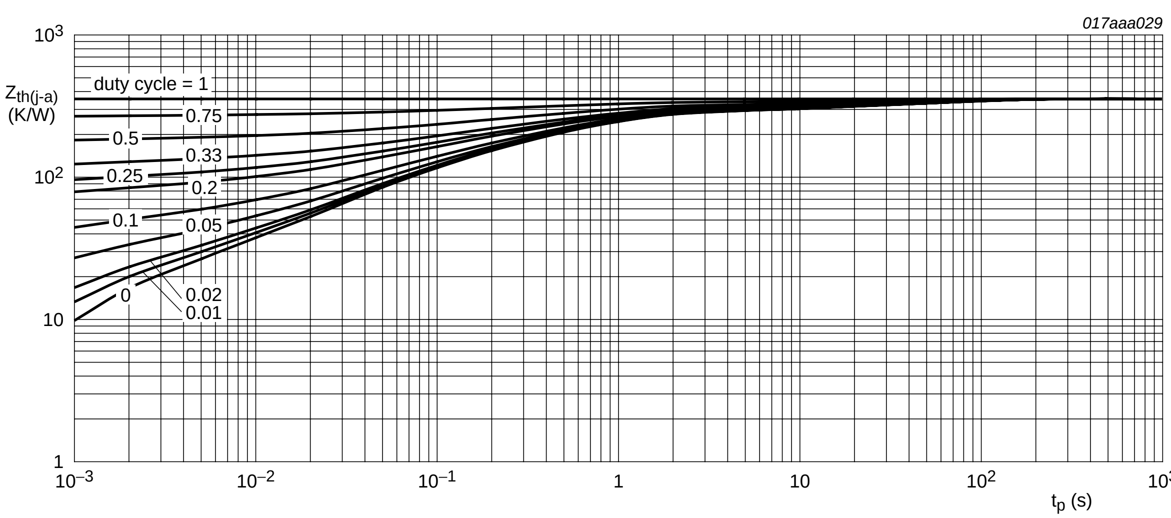
[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm^2.



FR4 PCB, standard footprint

Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



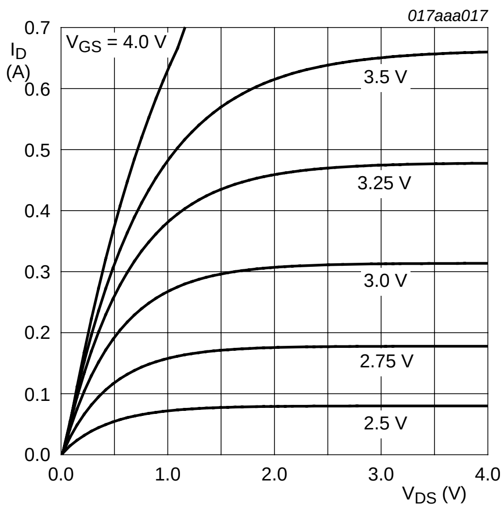
FR4 PCB, mounting pad for drain 1 cm^2

Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

7. Characteristics

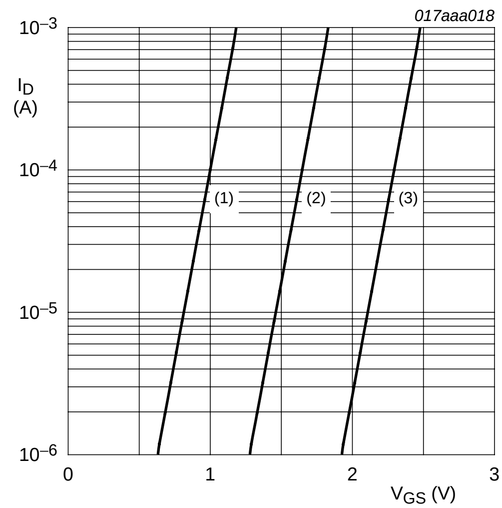
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	I_D = 10 µA; V_{GS} = 0 V; T_j = 25 °C	60	-	-	V
V_{GSth}	gate-source threshold voltage	I_D = 250 µA; V_{DS} = V_{GS}; T_j = 25 °C	1.1	1.75	2.4	V
I_{DSS}	drain leakage current	V_{DS} = 60 V; V_{GS} = 0 V; T_j = 25 °C	-	-	1	µA
		V_{DS} = 60 V; V_{GS} = 0 V; T_j = 150 °C	-	-	10	µA
I_{GSS}	gate leakage current	V_{GS} = 20 V; V_{DS} = 0 V; T_j = 25 °C	-	-	100	nA
		V_{GS} = -20 V; V_{DS} = 0 V; T_j = 25 °C	-	-	100	nA
R_{DSon}	drain-source on-state resistance	V_{GS} = 5 V; I_D = 50 mA; pulsed; t_p ≤ 300 µs; δ ≤ 0.01 ; T_j = 25 °C	-	1.3	2	Ω
		V_{GS} = 10 V; I_D = 500 mA; pulsed; t_p ≤ 300 µs; δ ≤ 0.01 ; T_j = 25 °C	-	1	1.6	Ω
g_{fs}	forward transconductance	V_{DS} = 10 V; I_D = 200 mA; pulsed; t_p ≤ 300 µs; δ ≤ 0.01 ; T_j = 25 °C	-	400	-	mS
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	I_D = 300 mA; V_{DS} = 30 V; V_{GS} = 4.5 V; T_j = 25 °C	-	0.6	0.8	nC
Q_{GS}	gate-source charge		-	0.2	-	nC
Q_{GD}	gate-drain charge		-	0.2	-	nC
C_{iss}	input capacitance	V_{GS} = 0 V; V_{DS} = 10 V; f = 1 MHz; T_j = 25 °C	-	30	50	pF
C_{oss}	output capacitance		-	7	-	pF
C_{rss}	reverse transfer capacitance		-	4	-	pF
$t_{d(on)}$	turn-on delay time	V_{DS} = 50 V; R_L = 250 Ω; V_{GS} = 10 V; $R_{G(ext)}$ = 6 Ω; T_j = 25 °C	-	3	6	ns
t_r	rise time		-	4	-	ns
$t_{d(off)}$	turn-off delay time		-	10	20	ns
t_f	fall time		-	5	-	ns
Source-drain diode						
V_{SD}	source-drain voltage	I_S = 115 mA; V_{GS} = 0 V; T_j = 25 °C	0.47	0.75	1.1	V



T_{amb} = 25 °C

Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values



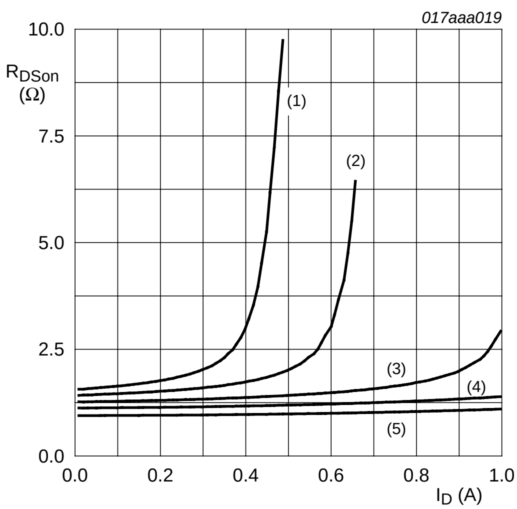
T_{amb} = 25 °C; V_{DS} = 5 V

(1) minimum values

(2) typical values

(3) maximum values

Fig 7. Sub-threshold drain current as a function of gate-source voltage



T_{amb} = 25 °C

(1) V_{GS} = 3.25 V

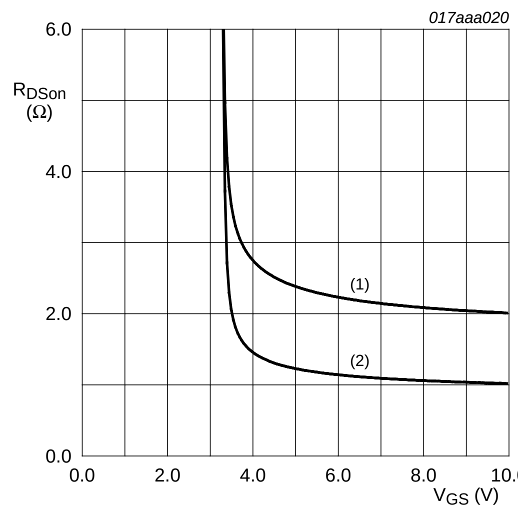
(2) V_{GS} = 3.5 V

(3) V_{GS} = 4 V

(4) V_{GS} = 5 V

(5) V_{GS} = 10 V

Fig 8. Drain-source on-state resistance as a function of drain current; typical values

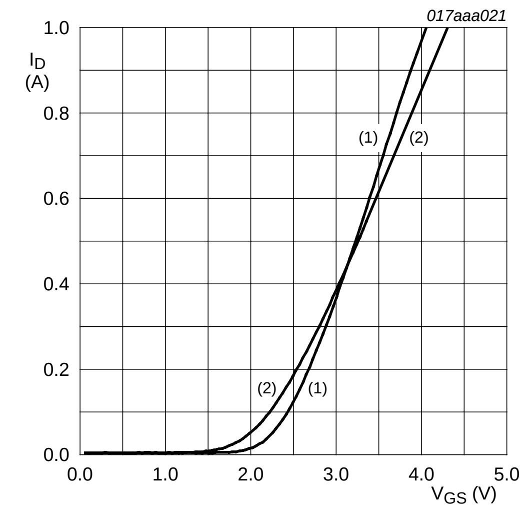


I_D = 500 mA

(1) T_{amb} = 150 °C

(2) T_{amb} = 25 °C

Fig 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

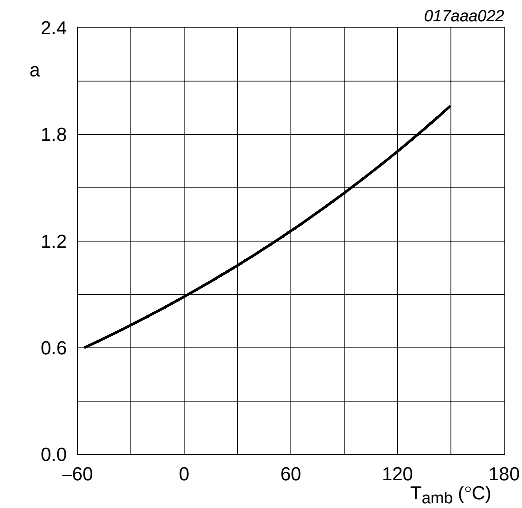


$V_{DS} > I_D \times R_{DSon}$

(1) T_{amb} = 25 °C

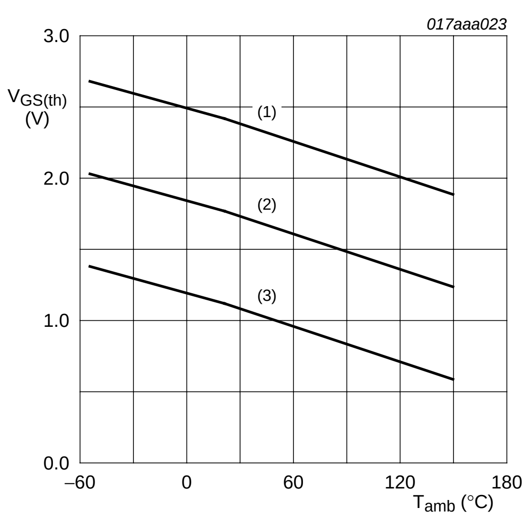
(2) T_{amb} = 150 °C

Fig 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values



$$a = \frac{R_{DSon}}{R_{DSon(25°C)}}$$

Fig 11. Normalized drain-source on-state resistance as a function of ambient temperature; typical values



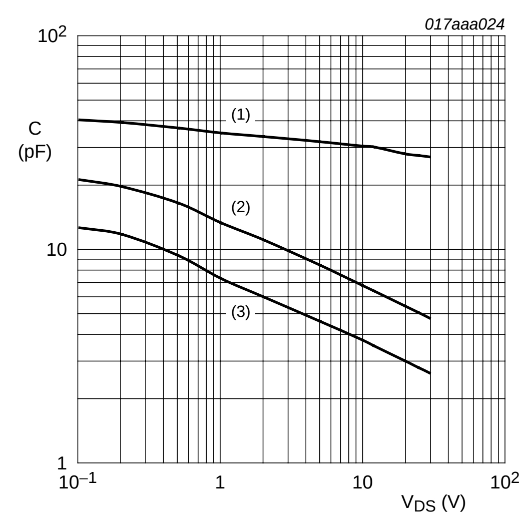
I_D = 0.25 mA; $V_{DS} = V_{GS}$

(1) maximum values

(2) typical values

(3) minimum values

Fig 12. Gate-source threshold voltage as a function of ambient temperature



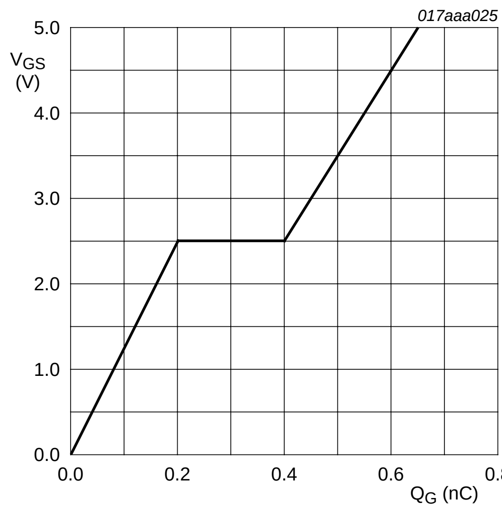
f = 1 MHz; V_{GS} = 0 V

(1) C_{iss}

(2) C_{oss}

(3) C_{rss}

Fig 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



I_D = 300 mA; V_{DS} = 30 V; T_{amb} = 25 °C

Fig 14. Gate-source voltage as a function of gate charge; typical values

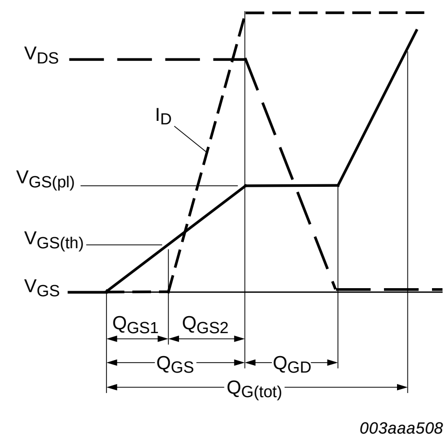
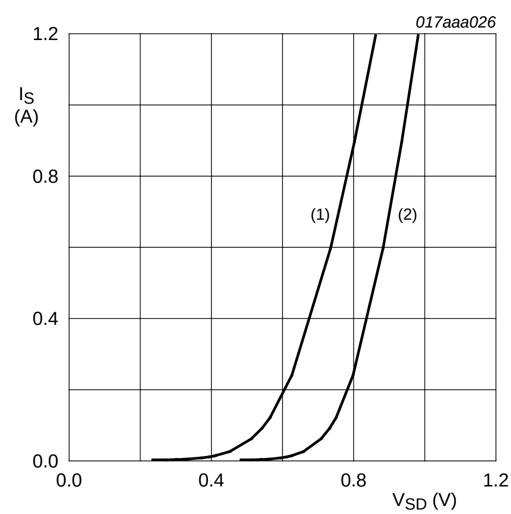


Fig 15. Gate charge waveform definitions



V_{GS} = 0 V

(1) T_{amb} = 150 °C

(2) T_{amb} = 25 °C

Fig 16. Source current as a function of source-drain voltage; typical values

8. Test information

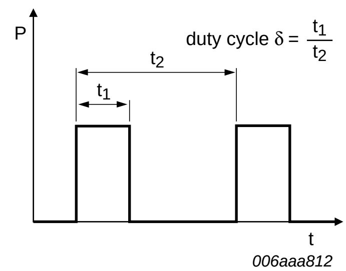
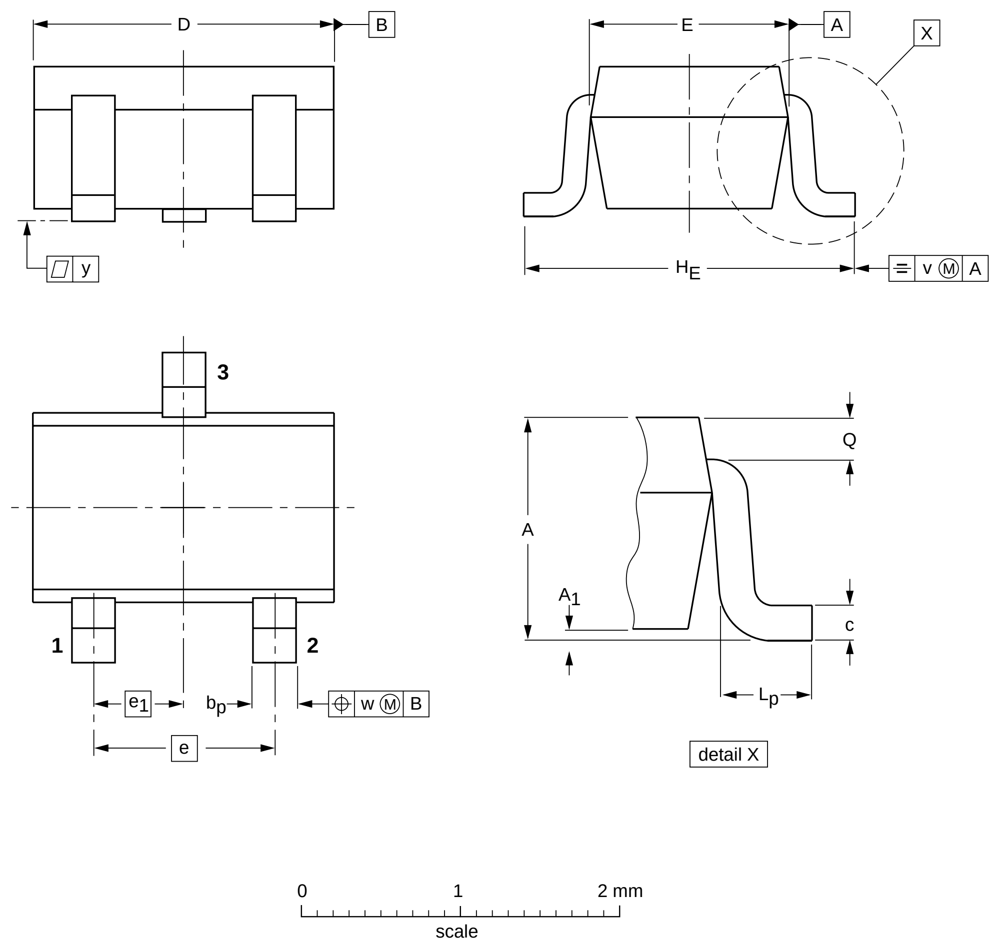


Fig 17. Duty cycle definition

9. Package outline

Plastic surface-mounted package; 3 leads **SOT323**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max	b_p	c	D	E	e	e_1	H_E	L_p	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT323			SC-70			~~04-11-04~~ 06-03-16

Fig 18. Package outline SOT323 (SC-70)

10. Soldering

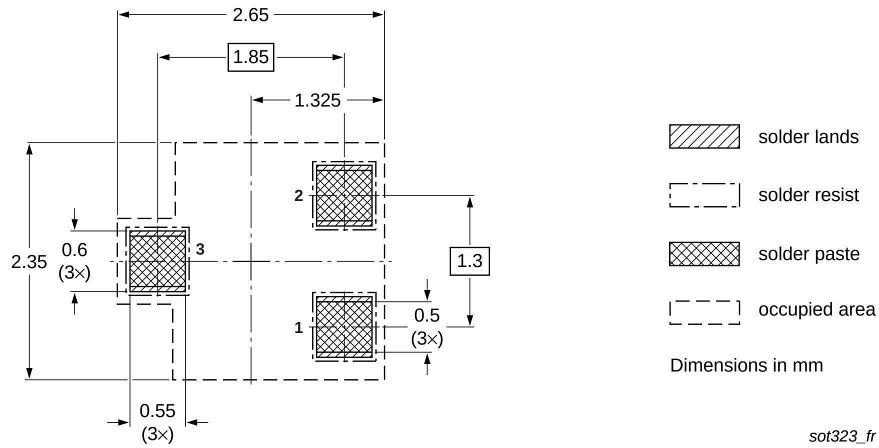


Fig 19. Reflow soldering footprint for SOT323 (SC-70)

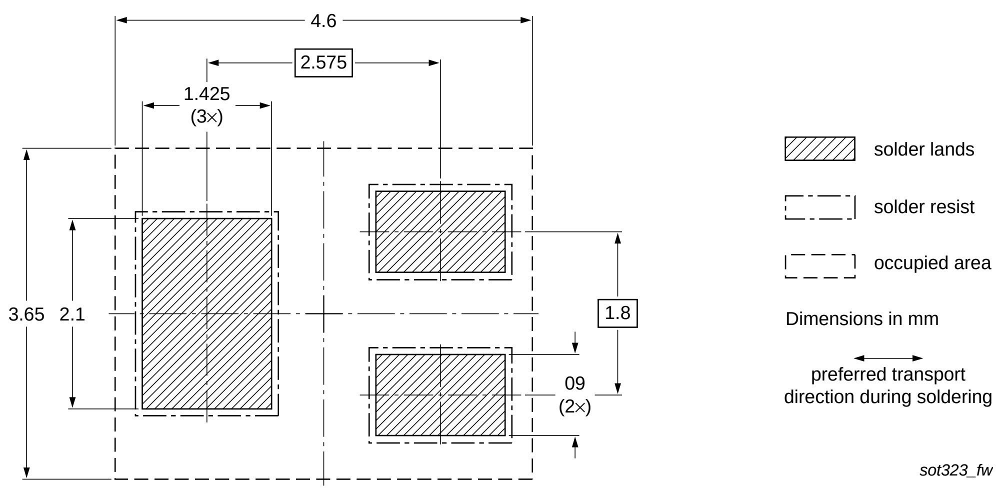


Fig 20. Wave soldering footprint for SOT323 (SC-70)

11. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
2N7002PW v.2	20100729	Product data sheet	-	2N7002PW_1
Modifications:	• Correction of thermal values. • Correction of various characteristics values including related graphs.			
2N7002PW_1	20100422	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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